BONDING APPARATUS AND BONDING TOOL CLEANING METHOD

ABSTRACT

In wire bonding in which a bonding tool is cleaned through plasma irradiation, the plasma application to a wire and therefore the formation of an unexpectedly large-sized ball in the following bonding operation is prevented. The cleaning of the bonding tool through plasma irradiation is followed by dummy bonding, the bonding tool is cleaned with a ball formed thereon, or a prohibition period is provided during which ball forming is prohibited until the energy of plasma attenuates after the bonding tool is cleaned to prevent the plasma irradiation from having an impact on the bonding operation so that the ball cannot have an increased diameter.

Figure 11